



### **Functional Block Diagram**



### **Pin Descriptions**

Pin Name	Pin No.	Description	
NC	1	No Connection	
VR <sub>OUT</sub>	2	Voltage Output	
NC	3	No Connection	
V <sub>IN</sub>	4	Supply Voltage	
NC	5	No connection	
VD <sub>OUT</sub>	6	V <sub>D</sub> Output (Reset on I/P)	
GND	7	Ground	
EN	8	Enable (V <sub>R</sub> On/Off)	



## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	KV
ESD MM	Machine Model ESD Protection	450	V
V <sub>IN</sub>	Input Voltage	+6	V
Ι <sub>ουτ</sub>	Output Current	$P_D/(V_{IN}-V_O)$	mA
VR <sub>OUT</sub>	Output Voltage	GND - 0.3 ~ V <sub>IN</sub> + 0.3	V
TJ	Operating Junction Temperature Range	-40 to +125	°C
T <sub>J(MAX)</sub>	Maximum Junction Temperature	150	°C
P <sub>D</sub>	Internal Power Dissipation	1.2	W

## **Recommended Operating Conditions**

Symbol	Parameter	Min	Max	Unit
V <sub>IN</sub>	Input Voltage	3.3	5.5	V
Ι <sub>Ουτ</sub>	I <sub>OUT</sub> Output Current		500	mA
T <sub>A</sub>	T <sub>A</sub> Operating Ambient Temperature		85	٥C





## Electrical Characteristics ( $V_{IN} = 12V$ , $T_A = +25$ °C, unless otherwise noted)

Symbol	Parameter	Test Conditions		Min	Тур.	Max	Unit
Ι <sub>Q</sub>	Quiescent Current	I <sub>O</sub> = 0mA		-	50	70	μA
1	Stondby Current	V <sub>EN</sub> = Off			15	30	
I <sub>STB</sub>	Standby Current	V <sub>IN</sub> = 5.0V					μA
	Output Voltage Accuracy	I <sub>O</sub> = 30mA, V <sub>IN</sub> = 5V		3.234	3.300	3.366	V
VR <sub>OUT</sub>	VR <sub>OUT</sub> Temperature Coefficient	-40°C to 85°C, I <sub>OUT</sub> = 30mA			±100		ppm °C
V <sub>DROPOUT</sub>	Dropout Voltage	I <sub>OUT</sub> = 100mA			100	250	mV
Ι <sub>Ουτ</sub>	Maximum Output Current	V <sub>IN</sub> = 5.3V		500			mA
I <sub>LIMIT</sub>	Current Limit	V <sub>IN</sub> = 5.3V			600		mA
I <sub>short</sub>	Short Circuit Current	V <sub>IN</sub> = 5.3V			50		mA
$\Delta V_{\text{LINE}} / \Delta V_{\text{IN}} / V R_{\text{OUT}}$	Line Regulation	$4.3V \le V_{IN} \le 5.5V$ ; $I_{OUT} = 30mA$			0.01	±0.2	%/V
$\Delta VR_{OUT}$	Load Regulation	$1\text{mA} \le I_{\text{OUT}} \le 100\text{mA}, V_{\text{IN}} = 5.3\text{V}$			15	50	mV
PSRR	Power Supply Rejection	V <sub>IN</sub> = 4.3V+ 0.5Vp- pAC, I <sub>OUT</sub> = 50mA	F= 1KHz		55		dB
V <sub>EH</sub>		Output ON		1.6			V
V <sub>EL</sub>	EN Input Threshold	Output OFF				0.25	V
I <sub>EN</sub>	Enable Pin Current			-0.1		0.1	μA
V <sub>DF</sub>	Detect fall voltage			3.83	3.91	3.98	V
V <sub>Hysteresis</sub>	$V_{D}$ Hysteresis Range			V <sub>DF</sub> x1.02	V <sub>DF</sub> x1.05	V <sub>DF</sub> x1.08	V
		VD <sub>OUT</sub> = 0.5V					mA
IVD <sub>OUT</sub>	VD Supply Current	$V_{IN} = 2.0V$			20		
		3.0V			30		
t <sub>RP</sub>	V <sub>DOUT</sub> Delay Time	V <sub>IN</sub> = 1.8V to VDF+ 1V		10	20	40	mSe
$\theta_{JA}$	Thermal Resistance Junction to Ambient	SOP-8L (Note 2)			134		°C/W
θ <sub>JC</sub>	Thermal Resistance Junction to Case	SOP-8L (Note 2)			28		°C/W

 $(T_A = 25^{\circ}C, C_{IN} = 1\mu F, C_{OUT} = 1\mu F, V_{EN} = V_{IN}, unless otherwise noted)$ 

Notes: 2. Test conditions for SOP-8L: Devices mounted on FR-4 PC board, MRP, 2oz copper layout, calibrate at  $T_J=150$  °C, measure at  $T_A=25^{\circ}$ C, minimum recommended pad layout



## 500mA CMOS LDO

## **Typical Performance Characteristics**





### 500mA CMOS LDO

#### **Typical Performance Characteristics (Continued)**





500mA CMOS LDO

#### **Timing Diagram**



#### Input Capacitor

A 1µF ceramic capacitor is recommended to connect between IN and GND pins to decouple input power supply glitch and noise. The amount of the capacitance may be increased without limit. A lower ESR (Equivalent Series Resistance) capacitor allows the use of less capacitance, while higher ESR type requires more capacitance. This input capacitor must be located as close as possible to the device to assure input stability and less noise. For PCB layout, a wide copper trace is required for both IN and GND.

#### **Output Capacitor**

The output capacitor is required to stabilize and help the transient response of the LDO. The AP7217 is designed to have excellent transient response for most applications with a small amount of output capacitance. The AP7217 is stable with any small ceramic output capacitors of  $1.0\mu$ F or higher value, and the temperature coefficients of X7R or X5R type. Additional capacitance helps to reduce undershoot and overshoot during transient. For PCB layout, the output capacitor must be placed as close as possible to OUT and GND pins, and keep the leads as short as possible.

#### **ENABLE/SHUTDOWN** Operation

The AP7217 is turned on by setting the EN pin high, and is turned off by pulling it low. If this feature is not used, the EN pin should be tied to IN pin to keep the regulator output on at all time. To ensure proper operation, the signal source used to drive the EN pin must be able to swing above and below the specified turn-on/off voltage thresholds listed in the Electrical Characteristics section under  $V_{IL}$  and  $V_{IH}$ .

	VRout	VD <sub>OUT</sub>
EN=0	0V	φ
EN=1	3.3V	φ

#### **Current Limit Protection**

When output current at OUT pin is higher than current limit threshold, the current limit protection will be triggered and clamp the output current to approximately 600mA to prevent over-current and to protect the regulator from damage due to overheating.



#### **Application Note**

#### Short circuit protection

When VRout pin is shorted to GND or VRout voltage is less than 200mV, short circuit protection will be triggered and clamp the output current to approximately 50mA.

#### VD<sub>OUT</sub> (reset output)

#### ---Open-Drain Active-Low reset output---

In general,  $VD_{OUT}$  is pulled up by a resistor (100Kohm) to  $V_{IN}$ . The AP7217 microprocess (uP) supervisory circuitry asserts a guaranteed logic-low reset during power-up and power-down. Reset is asserted asserts when  $V_{IN}$  is below the reset threshold and remain asserted for at least  $t_{RP}$  after  $V_{IN}$  rises above the reset threshold.

As long as  $V_{IN}$  is lower than the reset threshold,  $VD_{OUT}$  remains at logic "0". When  $V_{IN}$  become higher than  $V_{TH}$ , a logic "1" is asserted after a time delay defined by  $t_{RP}$ .

#### **Ordering Information**



	Device	Package	Packaging	13" Tape and Reel	
		Code	(Note 3)	Quantity	Part Number Suffix
Pb,	AP7217-33SG-13	S	SOP-8L	2500/Tape & Reel	-13

Notes: 3. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at http://www.diodes.com/datasheets/ap02001.pdf.

### **Marking Information**





## 500mA CMOS LDO

## Package Outline Dimensions (All Dimensions in mm)





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